

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V _{DSS}	-30	V
Gate-Source Voltage			V _{GSS}	±20	V
Continuous Drain Current (Note 5)	V _{GS} = -10V	T _A = +25°C T _A = +70°C	I _D	-400 -300	mA
Continuous Drain Current (Note 6)	V _{GS} = -10V	T _A = +25°C T _A = +70°C	I _D	-500 -400	mA
Pulsed Drain Current (Note 5)			I _{DM}	-1	A
Maximum Body Diode continuous Current			I _S	-800	mA

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Units
Total Power Dissipation	(Note 5)	P _D	0.5	W
	(Note 6)		1.2	
Thermal Resistance, Junction to Ambient	(Note 5)	R _{θJA}	273	°C/W
	(Note 6)		105	
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to 150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	-30	-	-	V	V _{GS} = 0V, I _D = -1mA
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	-	-	-1	μA	V _{DS} = -30V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	-	-	±10	μA	V _{GS} = ±16V, V _{DS} = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(th)}	-1.3	-	-2.3	V	V _{DS} = V _{GS} , I _D = -250μA
Static Drain-Source On-Resistance	R _{DS(on)}	-	-	2.4	Ω	V _{GS} = -10V, I _D = -200mA
				4		V _{GS} = -4.5V, I _D = -200mA
				16		V _{GS} = -2.5V, I _D = -10mA
Forward Transfer Admittance	Y _{fs}	-	6	-	S	V _{DS} = -10V, I _D = -400mA
Diode Forward Voltage	V _{SD}	-	0.8	1.2	V	V _{GS} = 0V, I _S = -300mA
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C _{iss}	-	51	-	pF	V _{DS} = -15V, V _{GS} = 0V, f = 1.0MHz
Output Capacitance	C _{oss}	-	11	-	pF	
Reverse Transfer Capacitance	C _{rss}	-	9	-	pF	
Total Gate Charge	Q _g	-	0.6	-	nC	V _{GS} = -4.5V V _{DS} = -10V, I _D = -200mA
Total Gate Charge	Q _g	-	1.3	-	nC	
Gate-Source Charge	Q _{gs}	-	0.2	-	nC	
Gate-Drain Charge	Q _{gd}	-	0.2	-	nC	V _{DS} = -15V, I _D = -500mA V _{GS} = -10V, R _G = 1 Ω
Turn-On Delay Time	t _{D(on)}	-	3.6	-	ns	
Turn-On Rise Time	t _r	-	8.5	-	ns	
Turn-Off Delay Time	t _{D(off)}	-	31.3	-	ns	
Turn-Off Fall Time	t _f	-	20.2	-	ns	

- Notes:
- Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
 - Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper pad layout
 - Short duration pulse test used to minimize self-heating effect.
 - Guaranteed by design. Not subject to production testing.

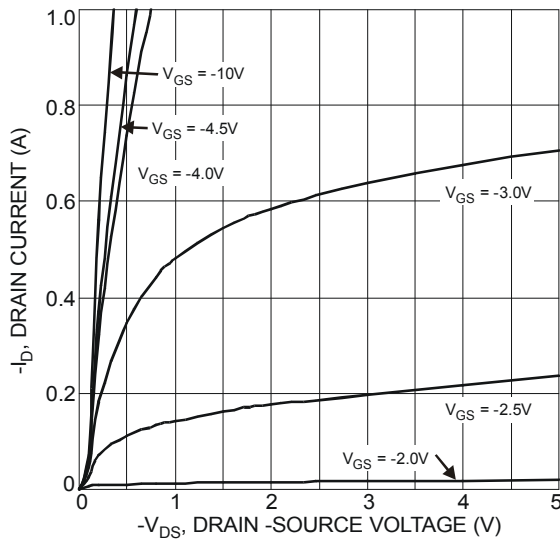


Figure 1 Typical Output Characteristics

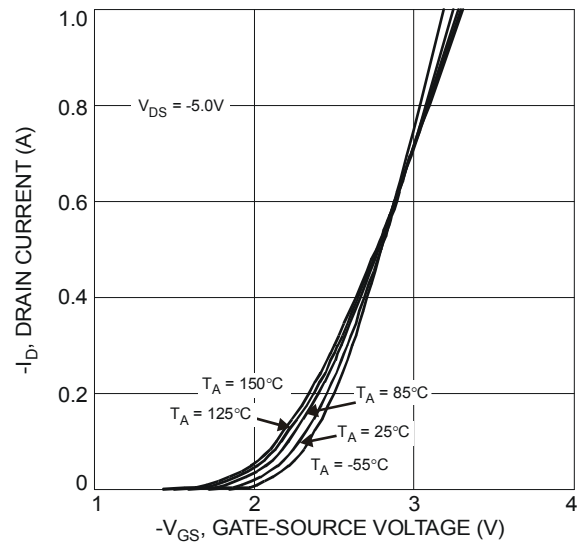


Figure 2 Typical Transfer Characteristics

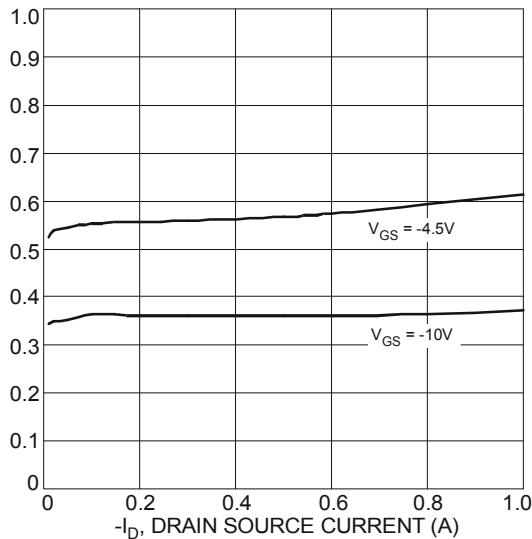


Figure 3 Typical On-Resistance vs. Drain Current and Gate Voltage

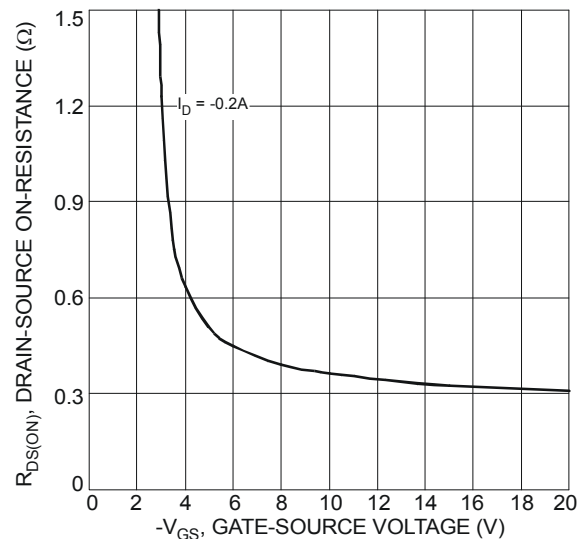


Figure 4 Typical Drain-Source On-Resistance vs. Gate-Source Voltage

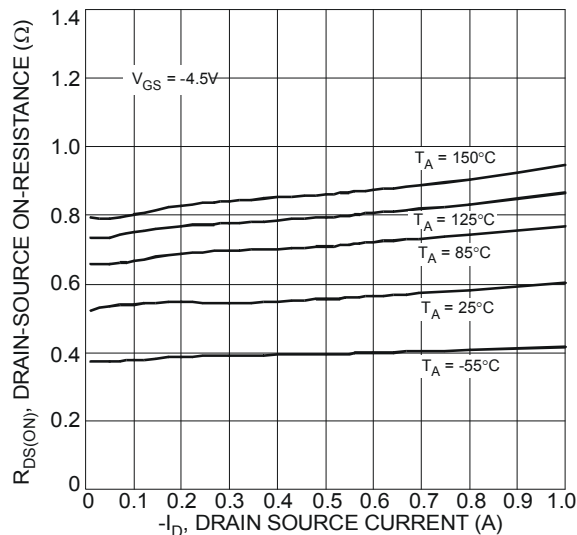


Figure 5 Typical On-Resistance vs. Drain Current and Temperature

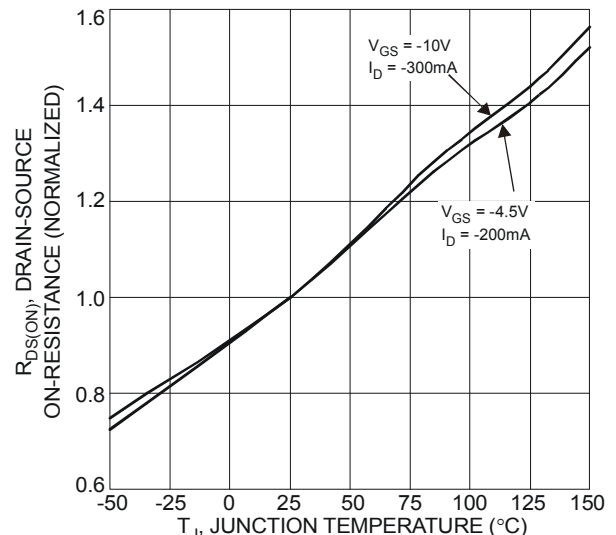
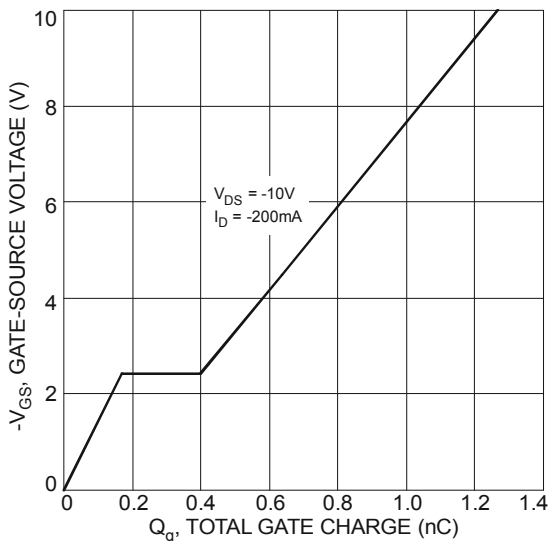
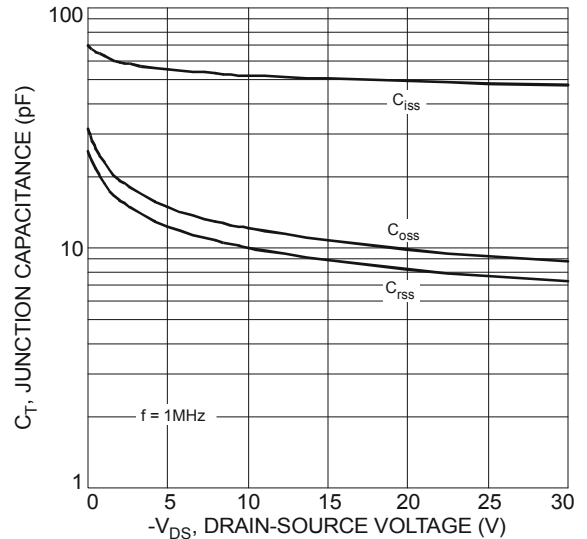
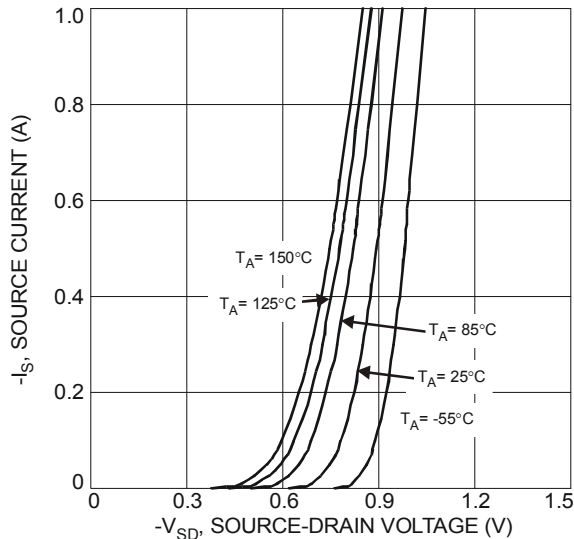
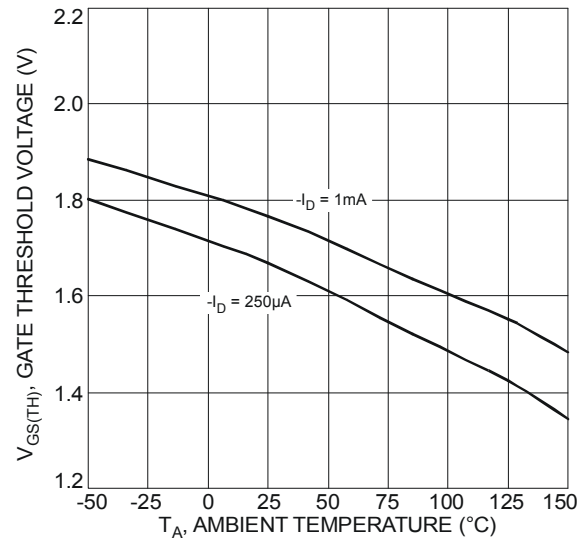
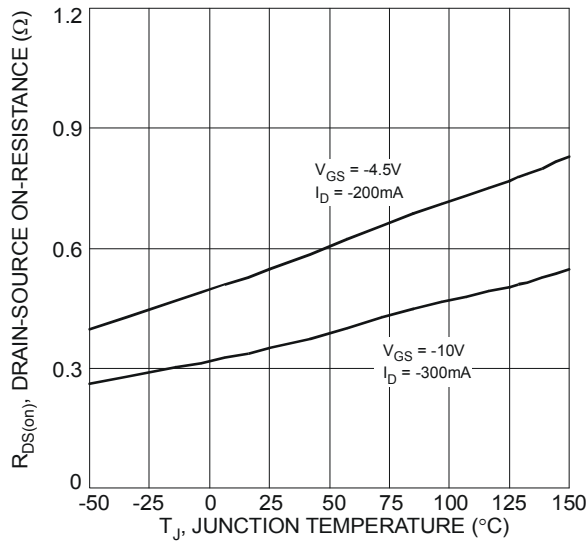
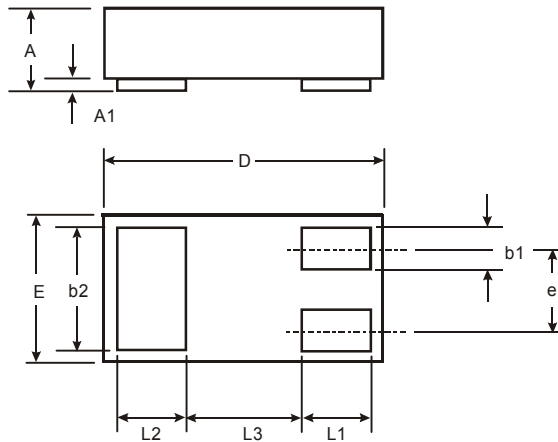


Figure 6 On-Resistance Variation with Temperature



Package Outline Dimensions

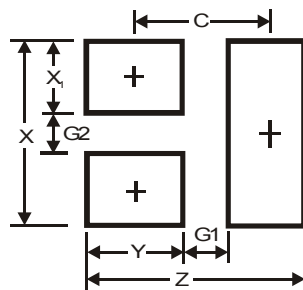
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



X1-DFN1006-3			
Dim	Min	Max	Typ
A	0.47	0.53	0.50
A1	0	0.05	0.03
b1	0.10	0.20	0.15
b2	0.45	0.55	0.50
D	0.95	1.075	1.00
E	0.55	0.675	0.60
e	—	—	0.35
L1	0.20	0.30	0.25
L2	0.20	0.30	0.25
L3	—	—	0.40
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
Z	1.1
G1	0.3
G2	0.2
X	0.7
X1	0.25
Y	0.4
C	0.7

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